TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

# **TPCA8105**

# Notebook PC Applications Portable Equipment Applications

- Small footprint due to compact and slim package
- Low drain-source ON resistance : RDS (ON) =  $23 \text{ m}\Omega$  (typ.)
- High forward transfer admittance :  $|Y_{fs}| = 14 \text{ S (typ.)}$
- Low leakage current :  $IDSS = -10 \mu A (VDS = -12 V)$
- Enhancement mode
  - :  $V_{th}$  = -0.5 to -1.2 V ( $V_{DS}$  = -10 V,  $I_{D}$  = -200  $\mu A$ )

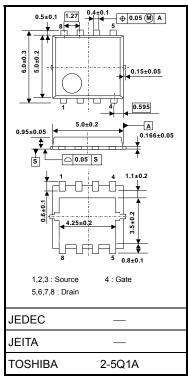
#### **Maximum Ratings (Ta = 25°C)**

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			$V_{DSS}$	-12	V	
Drain-gate volt	tage (R <sub>GS</sub> = 2	20 kΩ)	V <sub>DGR</sub>	-12	V	
Gate-source v	oltage		V <sub>GSS</sub>	±8	V	
Drain current	DC	(Note 1)	I <sub>D</sub>	-6	Α	
Dialii Cuiteili	Pulse	(Note 1)	I <sub>DP</sub>	-24	A	
Drain power dissipation (Tc = 25 °C)			$P_{D}$	20	W	
Drain power dissipation (t = 10 s) (Note 2a)			$P_{D}$	2.8		
Drain power dissipation (t = 10 s) (Note 2b)			$P_{D}$	1.6		
Single pulse avalanche energy (Note 3)		E <sub>AS</sub>	25.1	mJ		
Avalanche current		I <sub>AR</sub>	-6	Α		
Repetitive avalanche energy (Tc = 25 °C) (Note 4)		E <sub>AR</sub>	0.8	mJ		
Channel temperature		T <sub>ch</sub>	150	°C		
Storage temperature range		T <sub>stg</sub>	-55~150	°C		

Note: For (Note 1), (Note 2), (Note 3), (Note 4), refer to the next page.

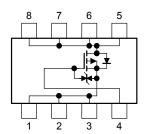
This transistor is an electrostatic-sensitive device. Handle with caution.

Unit: mm



Weight: 0.076 g (typ.)

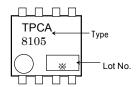
#### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc = 25 °C)	R <sub>th (ch-c)</sub>	6.25	°C/W
Thermal resistance, channel to ambient $(t=10 \text{ s}) \text{ (Note 2a)}$	R <sub>th (ch-a)</sub>	44.6	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-b)</sub>	78.1	C/VV

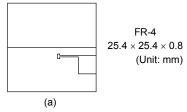
### Marking (Note 5)

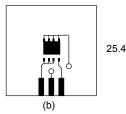


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$ 

Note 3:  $V_{DD} = -10$  V,  $T_{Ch} = 25^{\circ}C$  (initial), L = 0.5 mH,  $R_G = 25~\Omega,\, I_{AR} = -6.0~A$ 

Note 4: Repetitive rating: pulse width limited by maximum channel temperature.

Note 5: 

Weekly code: (Three digits)

Week of manufacture
(01 for first week of a year, continues up to 52 or 53)

Year of manufacture

(The last digit of the calendar year)

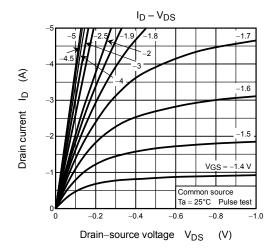
# **Electrical Characteristics (Ta = 25°C)**

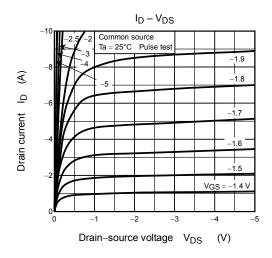
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	te leakage current		V <sub>GS</sub> = ±8 V, V <sub>DS</sub> = 0 V	_	_	±10	μА
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = -12 V, V <sub>GS</sub> = 0 V	10		-10	μΑ
Drain-source breakdown voltage		V (BR) DSS	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V -12	_	_	V	
		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$	-4	_	_	V
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -200 \mu\text{A}$	-0.5	_	-1.2	V
			V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -1.5 A	_	65	92	mΩ
Drain-source ON	resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -3.0 A	_	36	51	
			$V_{GS} = -4.5 \text{ V}, I_D = -3.0 \text{ A}$	_	23	33	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -3.0 \text{ A}$	7	14		S
Input capacitance		C <sub>iss</sub>		_	1600	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	260	_	
Output capacitan	ce	Coss		_	335	_	
Switching time Fall	Rise time	t <sub>r</sub>	$V_{GS} = \begin{array}{c} 0 \text{ V} \\ -5 \text{ V} \\ \hline \\ V_{DD} \simeq -6 \text{ V} \\ \end{array}$	_	7	_	ns
	Turn-on time	t <sub>on</sub>		_	13	_	
	Fall time	t <sub>f</sub>		_	21	_	
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>w</sub> = 10 μs	_	68	_	
Total gate charge (gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ -10 V, V <sub>GS</sub> = -5 V	_	18	_	nC
Gate-source charge		Q <sub>gs</sub>	I <sub>D</sub> = -6 A	_	14.5	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>		_	3.5	_	

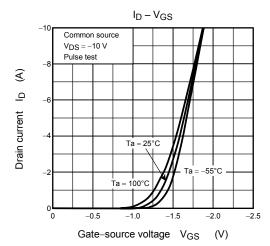
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

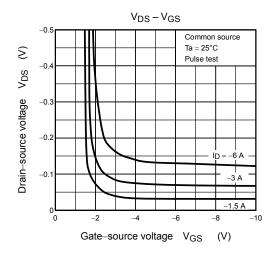
Characterist	ics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-24	Α
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = -6 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

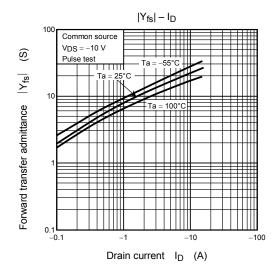
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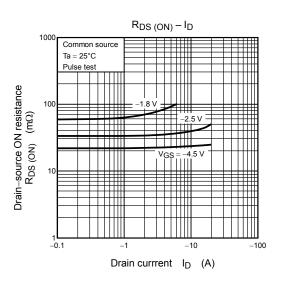


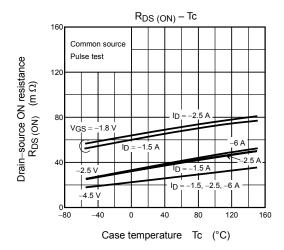


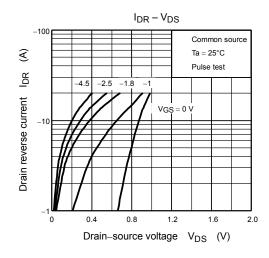


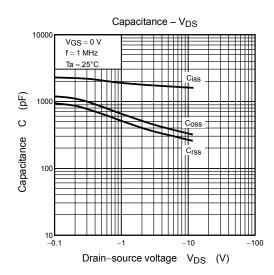


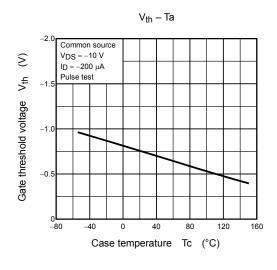


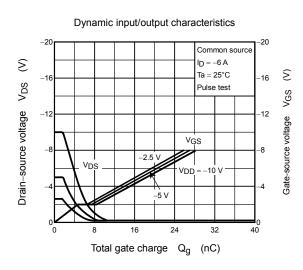




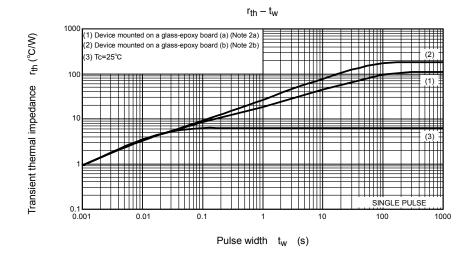


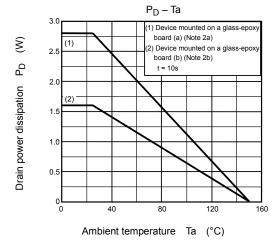


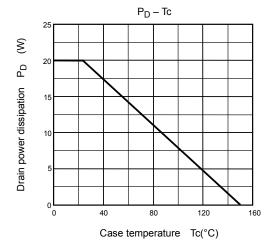


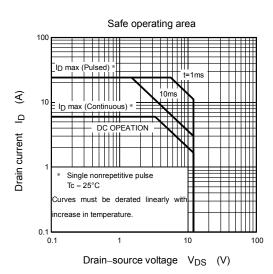


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